

Patent claims

1. Arrangement for the electrical connection of an optoelectronic component to an electrical component, having:
- an optoelectronic component with terminal contacts,
 - an electrical component with first electrical contacts and second electrical contacts,
 - a printed circuit board, to which the second electrical contacts of the electrical component are connected,
 - a flexible conductor arrangement of a planar form with a plurality of conductor tracks, the conductor arrangement
 - providing an electrical connection between the terminal contacts of the optoelectronic component and the first electrical contacts of the electrical component and, for this purpose,
 - having a first region with first contact regions and a second region with second contact regions, and
 - the optoelectronic component being mounted directly on the first region of the conductor arrangement and its terminal contacts being connected to the first contact regions of the conductor arrangement and/or
 - the electrical component being mounted directly on the second region of the conductor arrangement and its first electrical contacts being connected to the second contact regions of the conductor arrangement.
2. Arrangement according to Claim 1, the first region of the conductor arrangement being stiffened.

3. Arrangement according to Claim 2, the stiffened region of the conductor arrangement having a rigid part.
- 5 4. Arrangement according to Claim 1, the optoelectronic component being arranged in a package which is supported on the conductor arrangement.
- 10 5. Arrangement according to Claim 1, the second region of the conductor arrangement being stiffened.
- 15 6. Arrangement according to Claim 5, the stiffened region of the conductor arrangement having a rigid part.
- 20 7. Arrangement according to Claim 6, the second electrical contacts of the electrical component being electrically connected to the printed circuit board by means of electrical contacts of the rigid part.
- 25 8. Arrangement according to Claim 6, the electrical component being mechanically supported on the printed circuit board by means of the rigid part.
- 30 9. Arrangement according to Claim 1, the conductor arrangement running parallel to the printed circuit board and being supported by the printed circuit board in its second region.
10. Arrangement according to Claim 1, the electrical component being arranged in a package.
- 35 11. Arrangement according to Claim 10, the package being formed by a casting material, with which the electrical component is cast after an electrical

connection of the component to the conductor arrangement.

- 5 12. Arrangement according to Claim 1, the first region of the conductor arrangement and the second region of the conductor arrangement being formed at opposite ends of the conductor arrangement.
- 10 13. Arrangement according to Claim 12, the flexible conductor arrangement being bent in a third region, lying between the first region and the second region.
- 15 14. Arrangement according to Claim 1, the first region of the conductor arrangement being aligned substantially perpendicular to the second region of the conductor arrangement.
- 20 15. Arrangement according to Claim 1, the flexible conductor arrangement being formed by a flexible conductor.
- 25 16. Arrangement according to Claim 1, the conductor tracks of the conductor arrangement being impedance-matched.
- 30 17. Arrangement according to Claim 1, an electrical contact of the electrical component being connected to an assigned second contact region of the conductor arrangement by means of a bonding wire.
- 35 18. Arrangement according to Claim 1, a terminal contact of the optoelectronic component being connected to an assigned first contact region of the conductor arrangement by means of a bonding wire.

19. Arrangement according to Claim 1, the electrical component being formed by an unpackaged chip, which is mounted directly on the second region of the conductor arrangement.

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20. Arrangement according to Claim 19, the electrical component being a laser driver chip.

10 21. Arrangement according to Claim 1, the optoelectronic component being formed by an unpackaged chip, which is mounted directly on the first region of the conductor arrangement.

15 22. Arrangement according to Claim 21, the optoelectronic component being a laser chip.